

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4541628

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Tsuo-Wen Lu	08/01/2017
Chin-Wei Wu	08/01/2017
Tien-Chen Chan	08/01/2017
Ger-Pin Lin	08/01/2017
Shu-Yen Chan	08/01/2017
RECEIVING PARTY DATA	
Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN
Name:	FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.
Street Address:	6TH FLOOR, PODIUM OF ELECTRIC POWER COMPANY BUILDING, MEILING STREET, JINJIANG CITY
City:	QUANZHOU CITY, FUJIAN PROVINCE
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15672272
CORRESPONDENCE DATA	
Fax Number:	(703)997-4517
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3027291562
Email:	Patent.admin.uspto.cr@naipo.com
Correspondent Name:	WINSTON HSU
Address Line 1:	5F., NO.389, FUHE RD., YONGHE DIST.,
Address Line 4:	NEW TAIPEI CITY, TAIWAN
ATTORNEY DOCKET NUMBER:	NAUP3106USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/

PATENT

DATE SIGNED:	08/08/2017
Total Attachments: 10 source=2926060#page1.tif source=2926060#page2.tif source=2926060#page3.tif source=2926060#page4.tif source=2926060#page5.tif source=2926060#page6.tif source=2926060#page7.tif source=2926060#page8.tif source=2926060#page9.tif source=2926060#page10.tif	

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

SEMICONDUCTOR DEVICE AND FABRICATION METHOD THEREOF

As the below named inventor, I hereby declare that:
This declaration is directed to:

- ☒ The attached application, or
☐ United States application number _____ filed on _____, or
☐ PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

In consideration of the payment by **Fujian Jinhua Integrated Circuit Co., Ltd.** having a postal address of _____

6th floor, Podium of electric power company building, Meiling street, Jinjiang city, Quanzhou City, Fujian province 362200, P.R.C.

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I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.
IN WINTNESS WHEREOF, I have hereunto set hand and seal this AUG 01 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Tsuo-Wen Lu

Date: AUG 01 2017

Signature: Tsuo-Wen Lu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chin-Wei Wu

Date: AUG 01 2017

Signature: Chin-Wei Wu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Tien-Chen Chan**

Date: AUG 01 2017

Signature:

Tien Chen Chan

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Ger-Pin Lin

Date: AUG 0 1 2017

Signature: Ger-Pin Lin

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Shu-Yen Chan**

Date: AUG 01 2017

Signature: Shu Yen Chan